Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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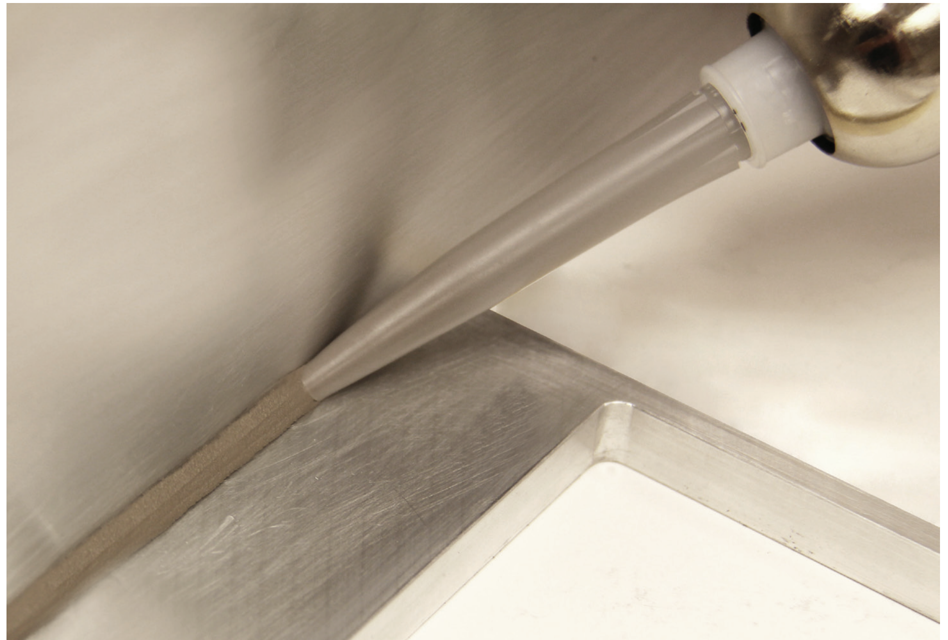
# CHO-BOND® 1075

## ONE COMPONENT CORROSION RESISTANT ELECTRICALLY CONDUCTIVE SILICONE SEALANT

### Customer Value Proposition:

CHO-BOND 1075 is a silver plated aluminum filled, one-component conductive silicone designed for use as a fillet, gap filler and seam sealant on electrical enclosures for EMI shielding or electrical grounding. Minimum recommended bond line for CHO-BOND 1075 is 0.010 inches (0.25mm). In addition, CHO-BOND 1075 may be used for EMI gasket repair, bonding, and attachment in applications where moderate strength (100 psi) is required. The silver aluminum filler of CHO-BOND 1075 provides excellent galvanic corrosion resistance when applied to aluminum substrates. No volatile organic compounds (VOCs) and minimal shrinkage upon curing make CHO-BOND 1075 a good choice for a variety of commercial and military applications. CHO-BOND 1075's moisture cure silicone polymer system allows it to cure to the touch in 24 hours and provides a robust conductive and environmental seal over a wide range of application temperatures.

For best adhesion results, CHO-BOND 1075 should be used in conjunction with CHO-SHIELD 1086 primer. Typical applications include man portable electronics, radar and communication systems, EMI vents, military ground vehicles, and shelters.



### Features and Benefits:

| | |
|---|---|
| • One component | • Easy to use, no weighing or mixing required. |
| • Silver plated aluminum filler | • Excellent conductivity 0.010 ohm-cm outstanding galvanic corrosion resistance against aluminum substrates. |
| • No VOCs | • Minimal shrinkage. |
| • Moisture cure silicone | • 15 minute working life, rapid skin formation, 24 hr handling time, requires no pressure during curing, wide range of application temperatures. 1 week for full cure. |
| • Light weight | • More coverage per gram of material, minimal weight added to assembly or vehicle. |
| • Non corrosive cure mechanism | • No corrosive by-products generated during curing to damage substrate. |
| • Dry medium paste | • Can be used on overhead or vertical surfaces. |

### Contact Information:

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# CHO-BOND 1075 - Product Information

## Table 1 Typical Properties

| CHO-BOND 1075 | | | |
|---|---|---|---|
| **Typical Properties** | **Typical Values** | **Test Method** | |
| Polymer | Silicone | N/A | |
| Filler | Silver-Plated Aluminum | N/A | |
| Mix Ratio, A : B (by weight) | 1-part | N/A | |
| Color | Gray | N/A | (Q) |
| Consistency | Dry Medium Paste | N/A | (Q) |
| Maximum DC Volume Resistivity | 0.010 ohm-cm | CHO-95-40-5555* | (Q/C) |
| Minimum Lap Shear Strength** | 100 psi (689 kPa) | CHO-95-40-5300* | (Q/C) |
| Minimum Peel Strength** | 4.0 lb./inch (700 N/m) | CHO-95-40-5302* | (Q/C) |
| Specific Gravity | 2.0 | ASTM D792 | (Q/C) |
| Hardness | 81 Shore A | ASTM-D2240 | (Q/C) |
| Continuous Use Temperature | - 55°C to 200°C (-67 °F to 392 °F) | N/A | (Q) |
| Elevated Temperature Cure Cycle | None | N/A | |
| Room Temperature Cure | 1 week*** | N/A | (Q) |
| Working Life | 0.25 hour | N/A | (Q) |
| Shelf Life, unopened | 6 months @ 25°C (77°F) | N/A | (Q) |
| Minimum thickness recommended | 0.010 in (0.25 mm) | N/A | |
| Maximum thickness recommended | 0.125 in (3.18 mm) | N/A | |
| Volatile Organic Content (VOC) | 0 g/l | Calculated | |
| Theoretical Coverage Area at 0.010" Thick per Pound (454 grams) | 1375 $in^2$ (8871 $cm^2$) | N/A | |
| Theoretical Coverage - Length of an 1/8" Diameter Bead per Pound (454 grams) | 90 feet (27.4 m) | N/A | |

**Notes:** N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test
* This test Method is available from Parker Chomerics.
** Minimum values listed are based on using the CHO-SHIELD 1086 primer that typically comes bundled with the CHO-BOND.
*** Cure is sufficient for handling in 24 hours. Full specification properties are developed after 1 week (168 hours) at room temperature.

## Table 2 Ordering Information

| Product | Weight (grams) | Packaging | Part Number | Primer Included |
|---|---|---|---|---|
| CHO-BOND 1075 | 71 | 1.5 fluid ounce foil tube | 50-02-1075-0000 | 1086 |
| | 71 | 1.5 fluid ounce foil tube | 50-02-1075-1000 | No |
| | 284 | 6 fluid ounce SEMCO cartridge | 50-01-1075-0000 | 1086 |

## Table 3 Primer Ordering Information

| Product | Weight (grams) | Packaging | Part Number |
|---|---|---|---|
| CHO-BOND 1086 | 10 | 3 dram glass vial | 50-10-1086-0000 |
| | 95 | 4 fluid ounce glass bottle | 50-04-1086-0000 |
| | 375 | 1 pint can | 50-01-1086-0000 |

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

**www.chomerics.com**
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